

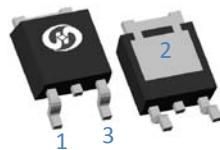
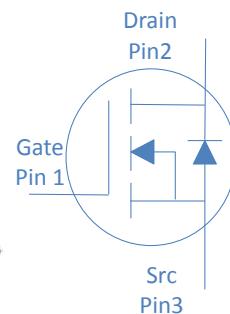
100V N-Ch Power MOSFET
Feature

- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free, Halogen Free

V_{DS}	100	V
$R_{DS(on),typ}$	$V_{GS}=10V$	15.5 mΩ
$R_{DS(on),typ}$	$V_{GS}=4.5V$	20.0 mΩ
I_D		45 A

Application

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ DC/DC in Telecoms and Industrial

TO-252

TO-251


Part Number	Package	Marking
HGI200N10SL	TO-251	GI200N10SL
HGD200N10SL	TO-252	GD200N10SL

Absolute Maximum Ratings at $T_j=25^\circ C$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^\circ C$	45	A
		$T_C=100^\circ C$	32	
Drain to Source Voltage	V_{DS}	-	100	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	200	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.4mH, T_C=25^\circ C$	45	mJ
Power Dissipation	P_D	$T_C=25^\circ C$	75	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 175	°C

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	65	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	2	°C/W

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	100	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	1.4	2.0	2.4	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}, T_j=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	-	15.5	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=10\text{A}$	-	20	26	
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=10\text{A}$	-	33	-	S
Gate Resistance	R_G	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	1.5	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=1\text{MHz}$	-	1350	-	pF
Output Capacitance	C_{oss}		-	104	-	
Reverse Transfer Capacitance	C_{rss}		-	7	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=50\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}$	-	19.9	-	nC
Total Gate Charge	$Q_g(4.5\text{V})$		-	8.5	-	
Gate to Source Charge	Q_{gs}		-	4.8	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	3.0	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=50\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	8	-	ns
Rise time	t_r		-	3	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	18	-	
Fall Time	t_f		-	3	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=10\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=50\text{V}, I_F=10\text{A}, dI_F/dt=500\text{A}/\mu\text{s}$	-	23	-	ns
Reverse Recovery Charge	Q_{rr}		-	98	-	nC

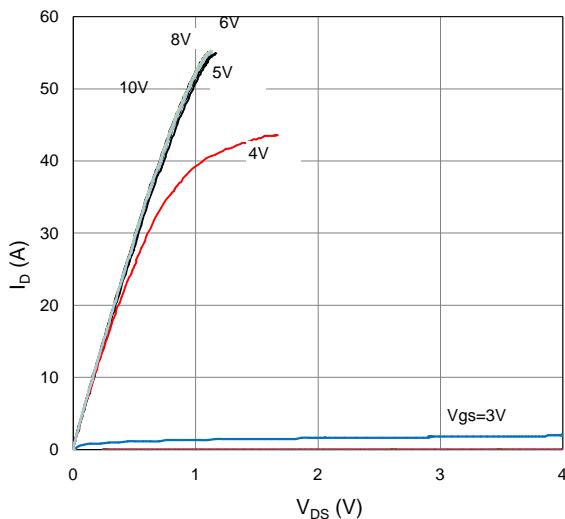
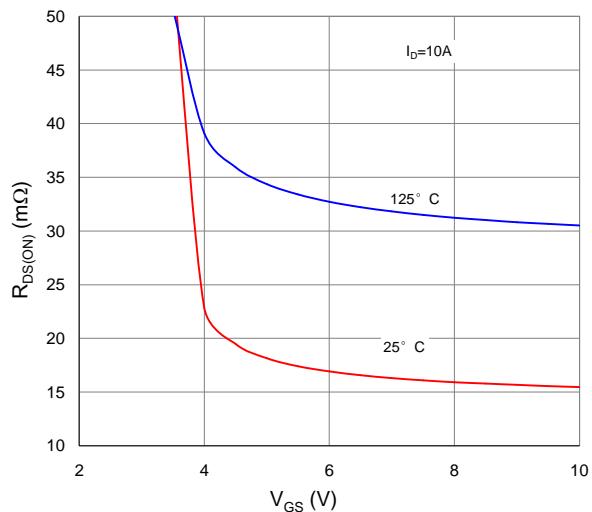
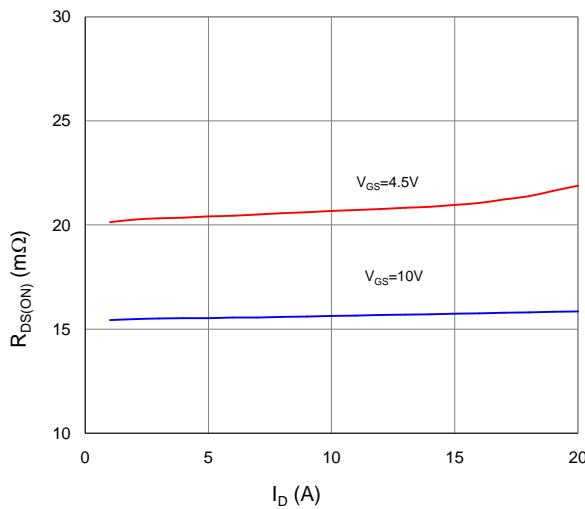
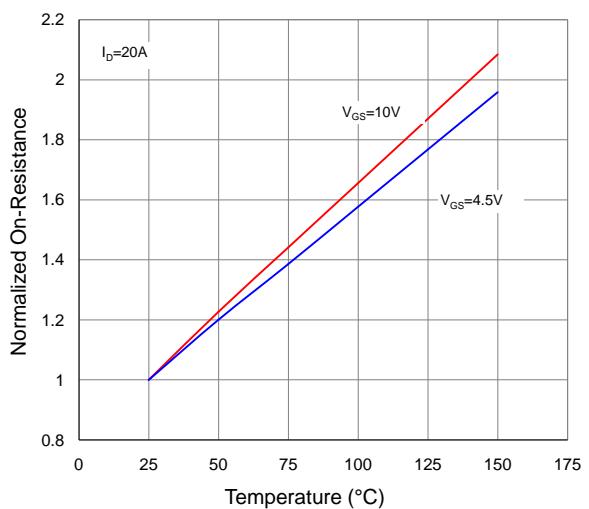
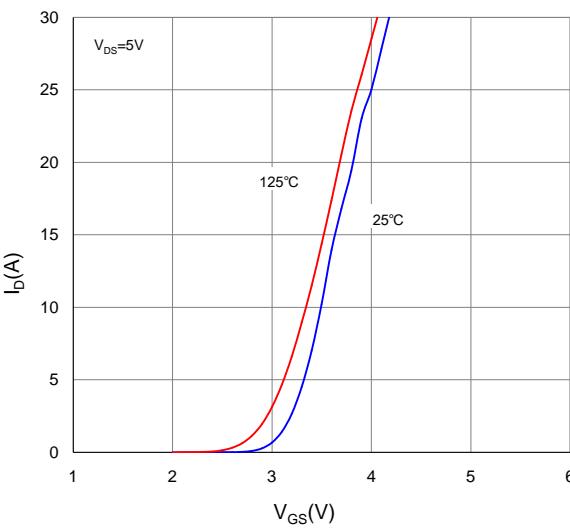
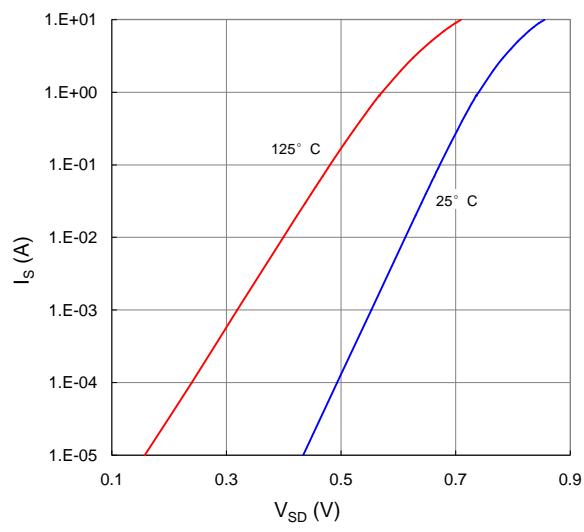
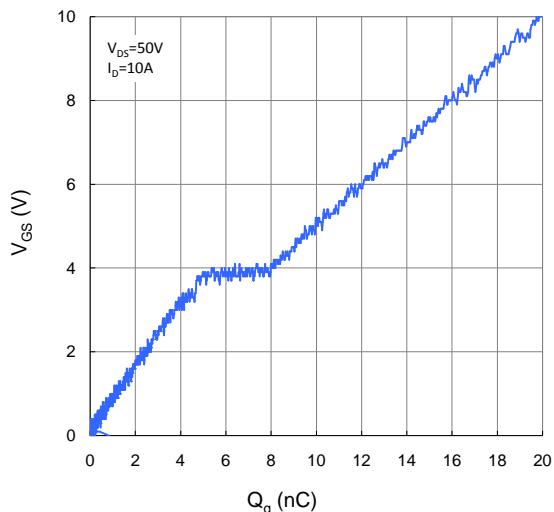
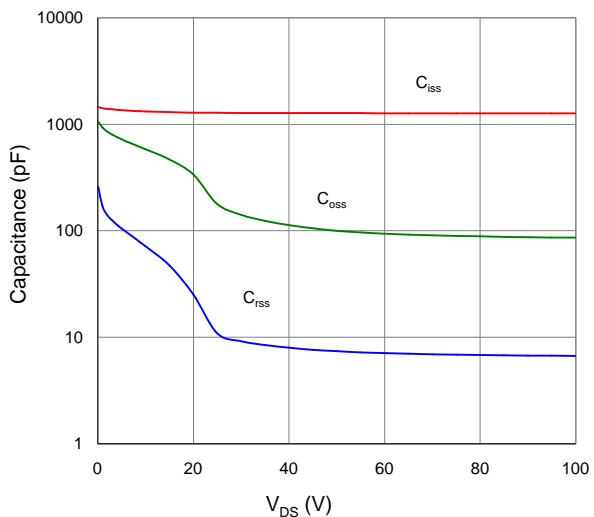
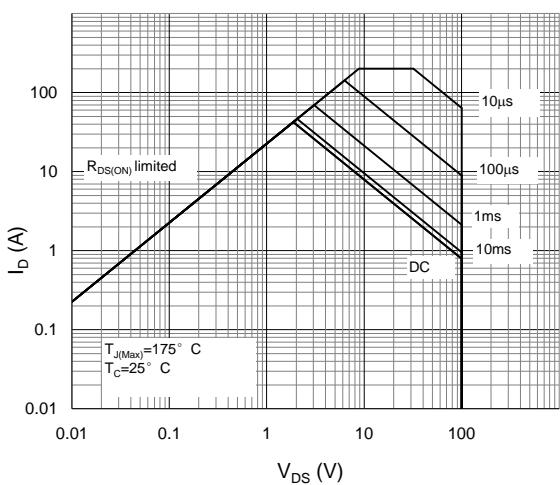
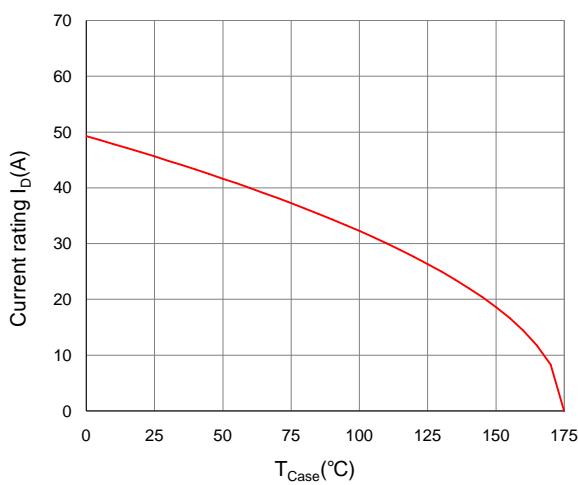
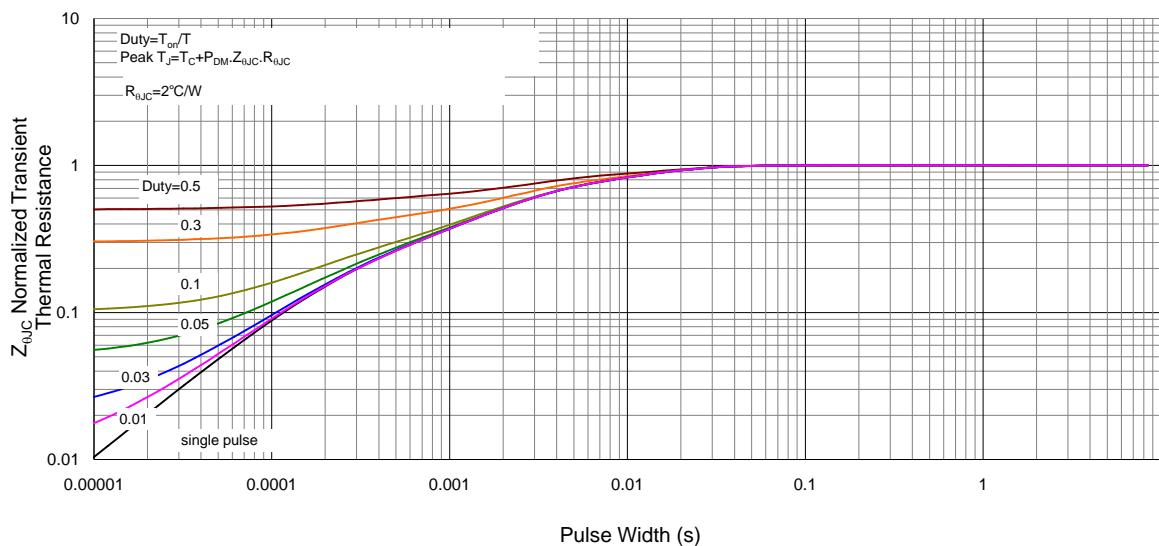
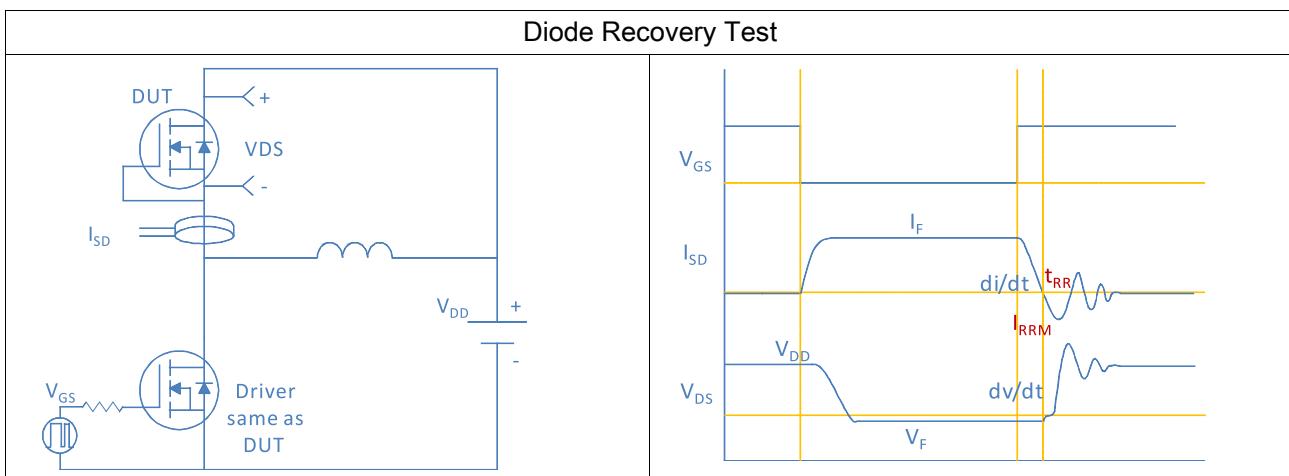
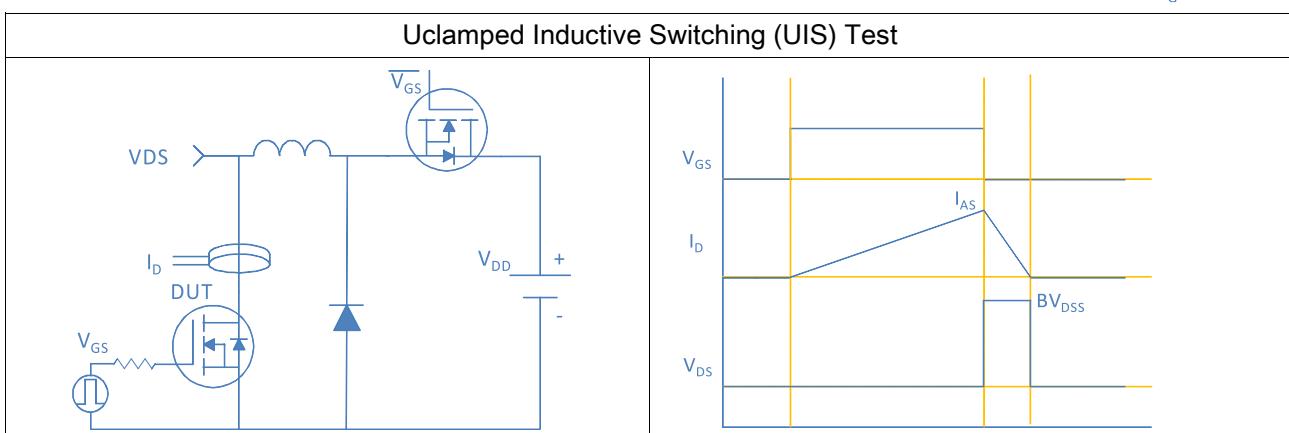
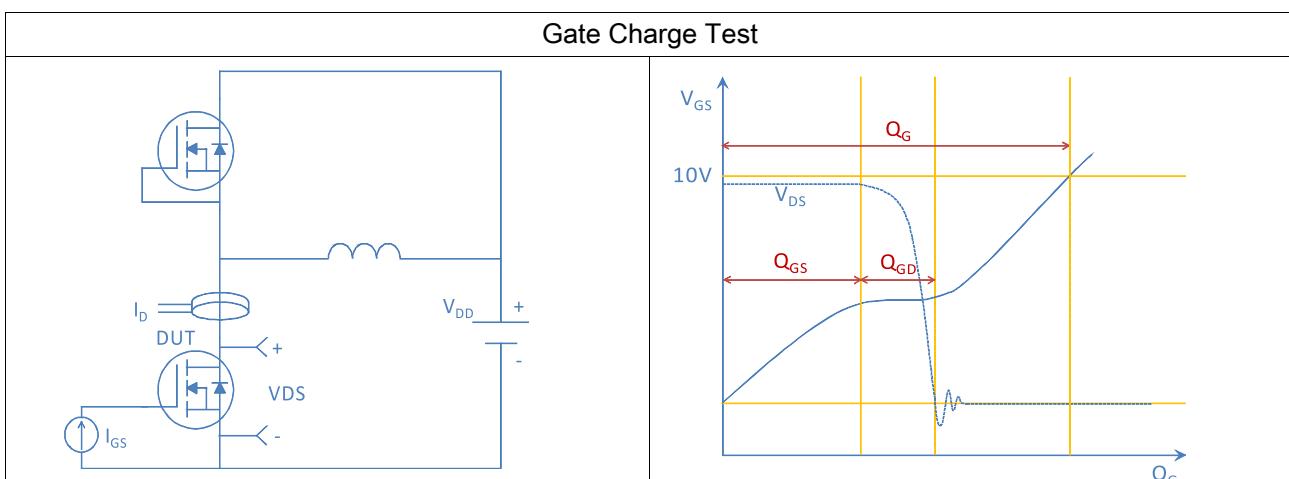
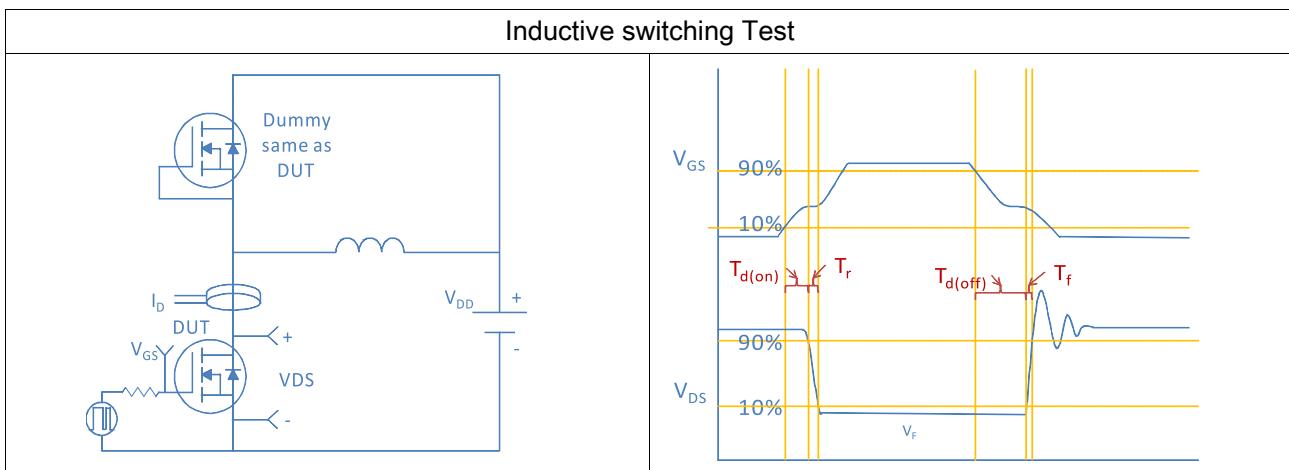
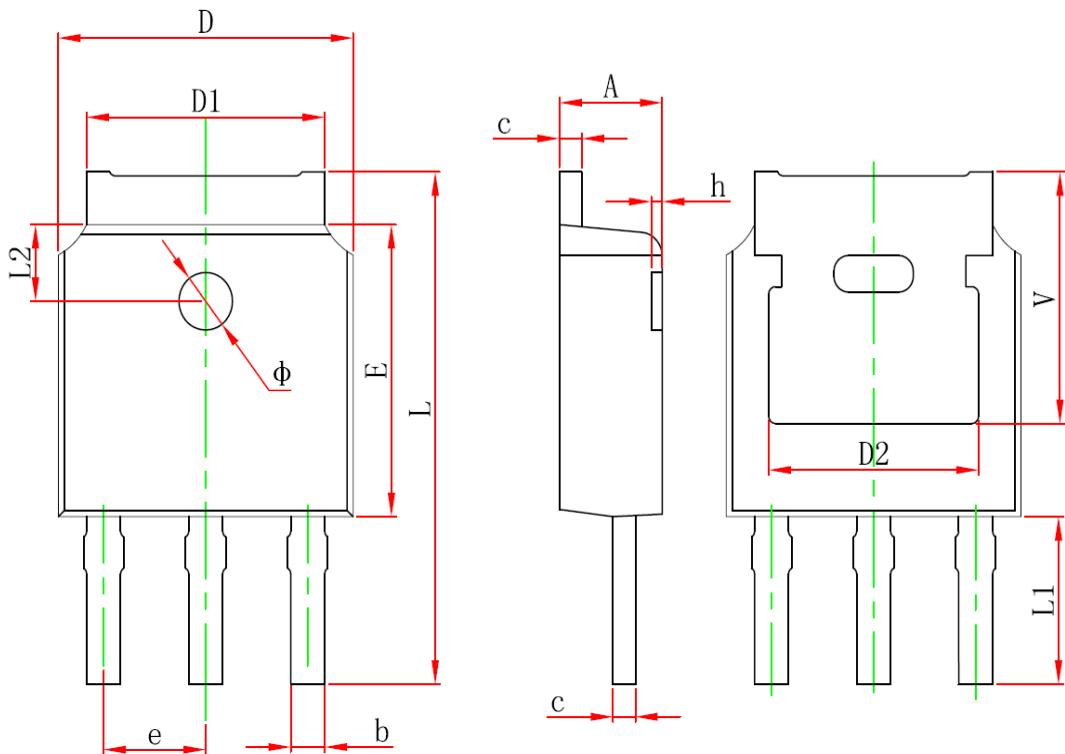
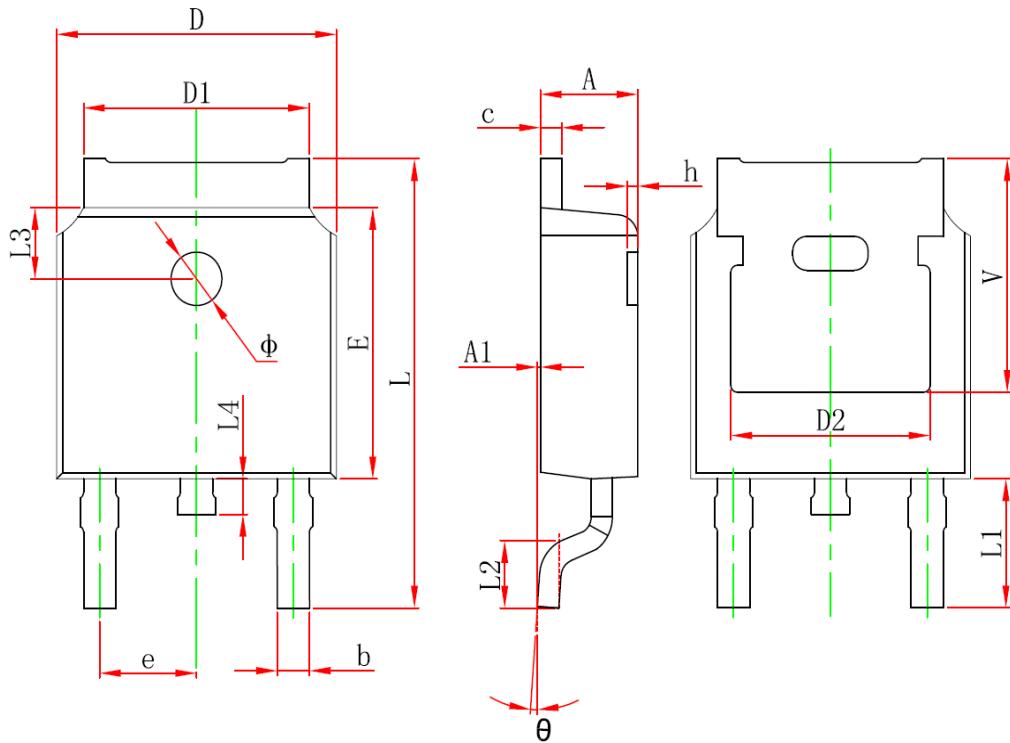
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case




Package Outline
TO-251, 3 leads


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	10.400	11.000	0.409	0.433
L1	3.500 REF.		0.138 REF.	
L2	1.600 REF.		0.063 REF.	
ϕ	1.100	1.300	0.043	0.051
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	

Package Outline
TO-252, 2 leads


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	